

## CIR-S3SUSKM1608G 1600MHz 8GB, (-)

DDR3 SO-DIMM 1600MHz 8GB

| Description   | Specifications         |                 |
|---|------------------------|-----------------|
| <p>The CIR-S3SUSKM1608G is 1024M words X 64 bits, 2 ranks. Unbuffered Small Outline Dual In-Line Memory Module (SO-DIMM). DDR3 SDRAMs in Fine Ball Grid Array (FBGA) packages on a 204pin glass-epoxy substrate. Provide a high performance 8 byte interface in 67.60mm width form factor of industry standard. It is suitable for easy interchange and addition.</p> | Density                | 8GB             |
|   | Pin Count              | 204pin          |
|   | Type                   | Unbuffered      |
|   | Dimensions             | 67.6mm x 30.0mm |
|   | ECC                    | Non-ECC         |
|   | Component Config       | 512M x 8 bit    |
|   | Data Rate              | 1600 MHz        |
|   | CAS Latency            | 11              |
|   | Voltage                | 1.5V            |
|   | PCB Layers             | 8               |
|   | Operating Temp.(TCASE) | 0°C~+85°C       |
|   | Module Ranks           | Dual Rank       |

### Features

- Data rate: 1600MHz
- 204pin, Small outline dual in-line memory module (SO-DIMM)
- Power supply: VDD= 1.5V + 0.075V
- Interface: SSTL\_15
- Programmable CAS Latency (CL): 6,7,8,9,10,11 support
- Fully differential clock inputs (CK, /CK) operation
- Differential Data Strobe (DQS, /DQS)
- DM masks write data-in at the both rising and falling edges of the data strobe
- BL switch on the fly
- 8banks
- 8K refresh cycles /64ms
- Dynamic On Die Termination supported
- Asynchronous RESET pin supported
- ZQ calibration supported
- TDQS (Termination Data Strobe) supported (x8 only)
- Write Levelization supported
- Refresh: Auto-Refresh, Self-Refresh
- On Die Thermal Sensor supported (JEDEC optional)
- 8 bit pre-fetch
- Lead-Free Products are RoHS compliant
- Average Refresh Period 7.8us at  $0^{\circ}\text{C} \leq \text{TC} \leq 85^{\circ}\text{C}$   
3.9us at  $85^{\circ}\text{C} \leq \text{TC} \leq 95^{\circ}\text{C}$

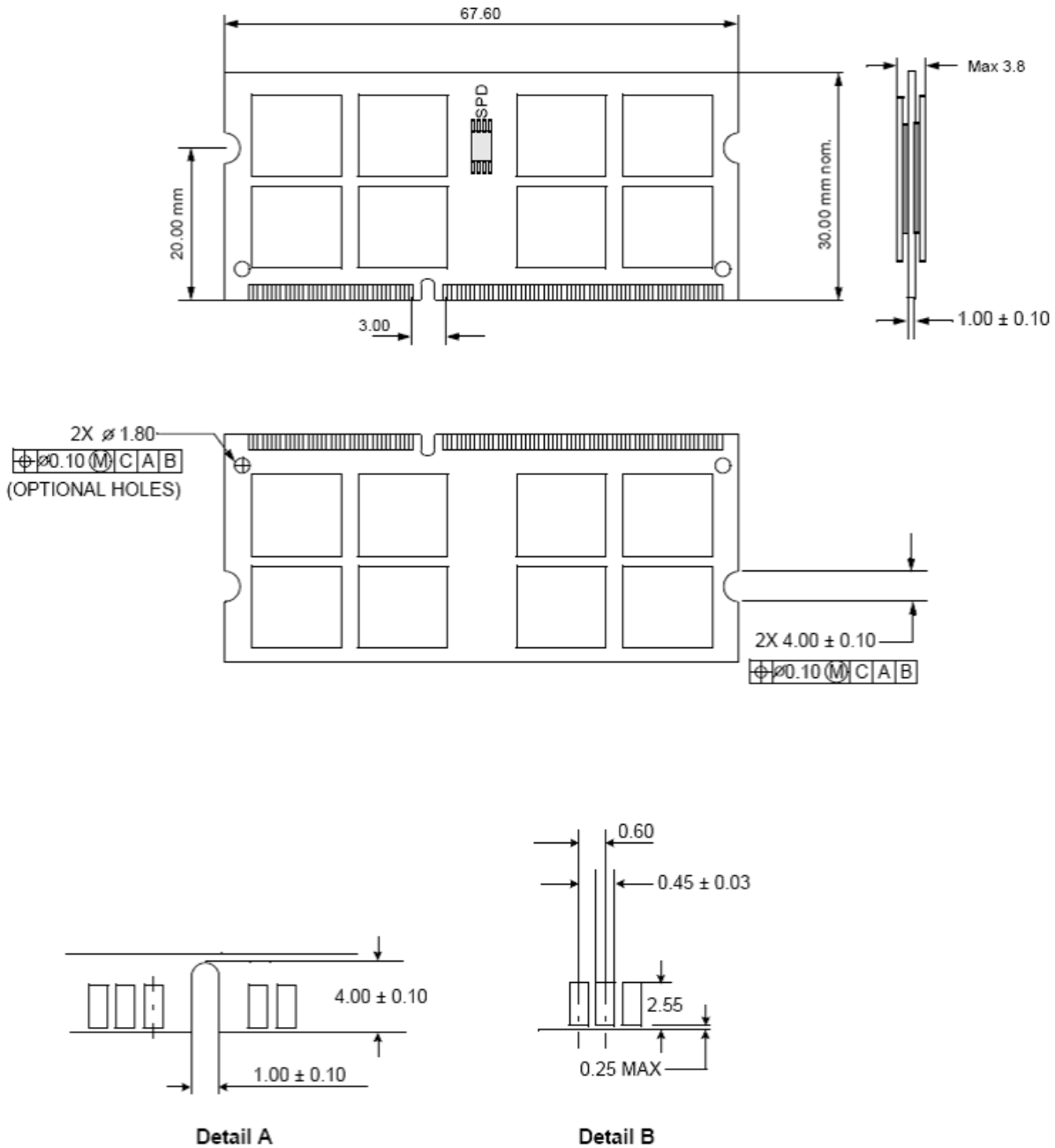


Speed Grade

| Frequency Grade | Data Transfer Rate | CAS Latency Support |      |      |      |      |      | CL-tRCD-tRP |
|-----------------|--------------------|---------------------|------|------|------|------|------|-------------|
|                 |                    | CL6                 | CL7  | CL8  | CL9  | CL10 | CL11 |             |
| DDR3-1600       | PC3-12800          | 800                 | 1066 | 1066 | 1333 | 1333 | 1600 | 11-11-11    |

Package Dimensions

Unit: mm



Tolerances : ± 0.15mm unless otherwise specified